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**Part Number:** [0512484799](#)  
**Status:** **Active**  
**Description:** 1.27mm (.050") Pitch Micro PGA Socket for Mobile Pentium\* 4, Ball Grid Array (BGA) Mount, ZIF, 479 Circuits, with Pick and Place Cover, Tape and Reel Package, 0.25µm (10µ") Gold (Au) Plating, Lead Free

**Documents:**

[3D Model](#) [RoHS Certificate of Compliance \(PDF\)](#)  
[Drawing \(PDF\)](#)

**General**

|                |                                |
|----------------|--------------------------------|
| Product Family | Processor Sockets              |
| Series         | <a href="#">51248</a>          |
| Comments       | ZIF, with Pick and Place Cover |
| Component Type | Socket                         |
| Product Name   | Micro PGA                      |

**Physical**

|                                |  |
|--------------------------------|--|
| Circuits (Loaded)              | 479                                    |
| Circuits (maximum)             | 479                                    |
| Color - Resin                  | Black, Natural                         |
| Durability (mating cycles max) | 50                                     |
| Material - Metal               | Copper-Nickel-Silicon, Stainless Steel |
| Material - Plating Mating      | Gold                                   |
| Material - Plating Termination | Nickel                                 |
| Material - Resin               | High Temperature Thermoplastic         |
| Packaging Type                 | Embossed Tape on Reel                  |
| Pitch - Mating Interface       | 1.27mm (.050")                         |
| Plating min - Mating           | 0.254µm (10µ")                         |
| Plating min - Termination      | 1.270µm (50µ")                         |
| Temperature Range - Operating  | -20°C to +90°C                         |
| Termination Interface: Style   | Surface Mount                          |

**Electrical**

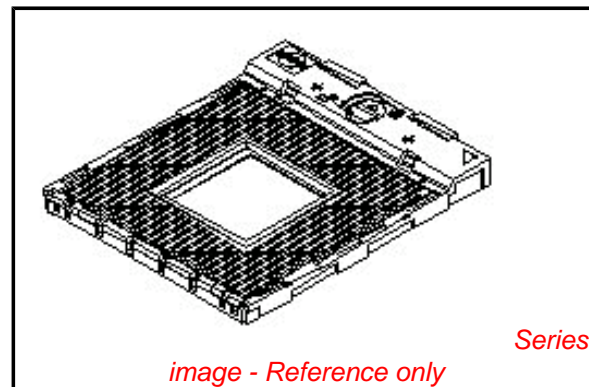
|                               |      |
|-------------------------------|------|
| Current - Maximum per Contact | 0.5A |
| Voltage - Maximum             | 100V |

**Solder Process Data**

|  |                           |
|--|---------------------------|
| Duration at Max. Process Temperature (seconds) | 10                        |
| Lead-free Process Capability                   | Reflow Capable (SMT only) |
| Max. Cycles at Max. Process Temperature        | 1                         |
| Process Temperature max. C                     | 250                       |

**Material Info**

\* Pentium and Celeron are registered trademark of Intel Corporation



**EU RoHS**

**ELV and RoHS  
Compliant**  
**REACH SVHC**  
 Not Reviewed  
**Low-Halogen Status**  
**Low-Halogen**

**China RoHS**



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**Search Parts in this Series**

[51248Series](#)

**Mates With**

Intel Mobile Celeron\* Processor-M|Intel Mobile Pentium\* 4 Processor